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L Number	Hits	Search Text	DB	Time stamp
1	50	(copper near clad) same (laser near5 (carbon near dioxide))	USPAT;	2003/01/13 10:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
		((corner peer cled) come (leger peer5 (corpon peer diovide)))	USPAT;	2003/01/13 10:14
2	2.	((copper near clad) same (laser near5 (carbon near dioxide))) and ((wav\$2 or corrugat\$3) same (copper near foil))	US-PGPUB;	2003/01/13 10.14
		and ((wavaz or corrugatas) same (copper near lon))	EPO; JPO;	
			DERWENT:	
	ļ	•	IBM_TDB	
3	494	((wav\$2 or corrugat\$3) same (copper near foil))	USPAT;	2003/01/13 09:36
	.0.	((Martin or considered) carrie (copper mean con))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
]			IBM_TDB	
4	15	( ((wav\$2 or corrugat\$3) same (copper near foil))) same	USPAT;	2003/01/13 09:36
		(copper near clad)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	205	(copper near3 particle) same (copper near foil)	USPAT;	2003/01/13 10:13
			US-PGPUB;	
ľ			EPO; JPO;	
			DERWENT;	
	407	(/fill) and (printed	IBM_TDB	2003/01/13 11:54
6	107	((copper near3 particle) same (copper near foil)) and (printed	USPAT;:: US-PGPUB;	2003/01/13 11.54
	!	near circuit near board or "PCB" or printed near wiring near	EPO; JPO;	
		board or "PWB")	DERWENT;	
			IBM_TDB	
7	5	(((copper near3 particle) same (copper near foil)) and (printed	USPAT;	2003/01/13 10:01
′	3	near circuit near board or "PCB" or printed near wiring near	US-PGPUB;	
		board or "PWB")) and ((copper near clad) same (laser near5	EPO; JPO;	
		(carbon near dioxide)))	DERWENT;	
		(	IBM_TDB	
8	2500	(copper near2 laminate) same (copper near foil)	USPAT;	2003/01/13 10:14
			US-PGPUB;	94 A 15 A
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/04/40 40 05
9	24	((copper near2 laminate) same (copper near foil)) and ((wav\$2	USPAT;	2003/01/13 10:35
		or corrugat\$3) same (copper near foil))	US-PGPUB;	
			EPO; JPO; DERWENT;	'
i			IBM_TDB	
10	2	(((copper near2 laminate) same (copper near foil)) and	USPAT:	2003/01/13 10:30
10	2	(((copper riearz familiate) same (copper riear foil))) and ((copper liear foil))) and ((copper liear foil)))	US-PGPUB;	2000/01/10 10:00
	•	near clad) same (laser near5 (carbon near dioxide)))	EPO; JPO;	į.
		The stary same faces heard (same in hear disking)	DERWENT;	
			IBM_TDB	
11	3	(((copper near2 laminate) same (copper near foil)) and	USPAT;	2003/01/13 10:31
	J	((wav\$2 or corrugat\$3) same (copper near foil))) and (laser	US-PGPUB;	
İ		near5 (carbon near dioxide))	EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
12	17	(bulk near copper) same (copper near foil)	USPAT;	2003/01/13 10:35
ļ			US-PGPUB;	
			EPO; JPO;	·
			DERWENT;	
40		(/b. II	IBM_TDB USPAT;	2003/01/13 10:36
13	8	((bulk near copper) same (copper near foil)) and rough\$3		2003/01/13 10.30
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
			USPAT;	2002/04/42 44:52
14	1764	plat\$3 same (copper near clad)	LUSPAT:	2003/01/13 11:52

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15	608	(plat\$3 same (copper near clad)) and (resist same etch\$3)	USPAT; US-PGPUB	2003/01/13 11:53
16	517	((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/13 12:29
17	517	(((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<200000516	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:00
18	517	((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")	USPAT; US-PGPUB	2003/01/13 12:00
19	398	(((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<20000516	USPAT; US-PGPUB	2003/01/13 12:01
20	336	(via or hole or open\$3) same (laser near (carbon near dioxide))	USPAT; US-PGPUB	2003/01/13 12:03
21	3	(((((plat\$3 same (copper near clad)) and (resist same etch\$3)) and (printed near circuit near board or "PCB" or printed near wiring near board or "PWB")) and @pd<20000516) and ((via or hole or open\$3) same (laser near (carbon near dioxide)))	USPAT; US-PGPUB	2003/01/13 12:04
22	2106	(printed near wiring near board or "PWB") and (plat\$3 same via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:43
23	3	( (printed near wiring near board or "PWB") and (plat\$3 same via)) and (bulk near copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:41
24	361	( (printed near wiring near board or "PWB") and (plat\$3 same via)) and (etch\$3 same resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/13 12:44
25	172	(( (printed near wiring near board or "PWB") and (plat\$3 same via)) and (etch\$3 same resist)) and @pd<20000516	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:45
26	3	((( (printed near wiring near board or "PWB") and (plat\$3 same via)) and (etch\$3 same resist)) and @pd<20000516) and ((copper near clad) same laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 12:46